Process / Product Change Notification

infineon

N° 865-DISTI42-C4002348-Private

Dear Customer,

Please find attached our INFINEON Technologies PCN:

GEM Shanghai (China) will change the assembly Bill of Materials for the DPak products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 15-July-2016.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Arunjai Mittal
Registered Office: Neubiberg
Commercial Register: München HRB 126492



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GEM Shanghai (China) will change the assembly Bill of Materials for the DPak products

► Products affected:

| Sales Name | SP N° | OPN | Package |
|-----------------|-------------|-----------------|-----------|
| IRG4RC10KDTRPBF | SP001535994 | IRG4RC10KDTRPBF | DPAKCOPAK |
| IRG4RC10SDTRPBF | SP001542118 | IRG4RC10SDTRPBF | DPAKCOPAK |
| IRG4RC20FTRLPBF | SP001541522 | IRG4RC20FTRLPBF | DPAK |
| IRGR3B60KD2TRP | SP001534036 | IRGR3B60KD2TRP | DPAKCOPAK |

▶ Detailed Change Information:

Subject: Bill of Materials and Package Outline Dimension (POD) change

Reason: Bill of Materials consolidation

Description: GEM Shanghai (China) will change the assembly Bill of Materials for the DPak products

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As the result of this change, the Bill of Materials and package dimensions will change as follows:

| Material | OLD | NEW |
|-----------------------------|-----------|-----------|
| Mold Compound | # 44-0287 | # 44-1489 |
| Dimension | | |
| Heatsink (D1) | 346 | 4 |
| Die attach paddle thickness | 0.508 | 0.508 |

▶ Product Identification: By date code and lot code product marking.

▶ Impact of Change: No impact is expected. The new Bill of Materials will meet the same qualification level of the existing product.

► Attachments:

► Time Schedule:

Final qualification report: Available

First samples available: Available

Intended start of delivery: 27-July-2016

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If you have any questions, please do not hesitate to contact your local Sales office.